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MOSFETs Silicon N-channel MOS (U-MOSⅧ)

TPN2R203NC

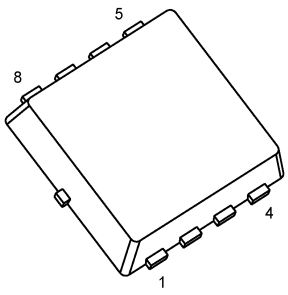
1. Applications

- Power Management Switches

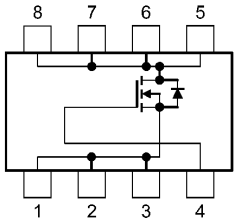
2. Features

(1) Low drain-source on-resistance: $R_{DS(ON)}$ = 1.8 mΩ (typ.) (V_{GS} = 10 V)
(2) Low leakage current: I_{DSS} = 10 μA (max) (V_{DS} = 30 V)
(3) Enhancement mode: V_{th} = 1.3 to 2.3 V (V_{DS} = 10 V, I_D = 0.5 mA)

3. Packaging and Internal Circuit



TSON Advance



1, 2, 3: Source
4: Gate
5, 6, 7, 8: Drain

4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	30	V
Gate-source voltage			V_{GSS}	±20	V
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I_D	100	A
Drain current (DC)	(T_c = 25 °C)	(Note 1)	I_D	45	A
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I_{DP}	200	A
Power dissipation	(T_c = 25 °C)		P_D	42	W
Power dissipation	(t = 10 s)	(Note 3)	P_D	1.9	W
Power dissipation	(t = 10 s)	(Note 4)	P_D	0.7	W
Single-pulse avalanche energy		(Note 5)	E_{AS}	126	mJ
Avalanche current			I_{AR}	45	A
Channel temperature			T_{ch}	150	°C
Storage temperature			T_{stg}	-55 to 150	°C

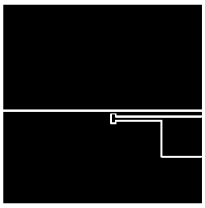
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production
2013-05

5. Thermal Characteristics

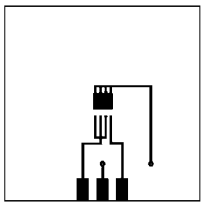
Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T_c = 25 °C)		$R_{th(ch-c)}$	2.97	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	$R_{th(ch-a)}$	65.7	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 4)	$R_{th(ch-a)}$	178	°C/W

Note 1: Ensure that the channel temperature does not exceed 150 °C.
Note 2: Limited by silicon chip capability.
Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1
Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2
Note 5: V_{DD} = 24 V, T_{ch} = 25 °C (initial), L = 0.048 mH, I_{AR} = 45 A



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

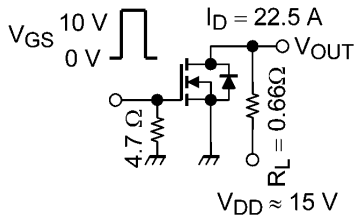
6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	—	—	±0.1	μA
Drain cut-off current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V	—	—	10	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	I_D = 10 mA, V_{GS} = 0 V	30	—	—	V
Drain-source breakdown voltage (Note 6)	$V_{(BR)DSX}$	I_D = 10 mA, V_{GS} = -20 V	15	—	—	V
Gate threshold voltage	V_{th}	V_{DS} = 10 V, I_D = 0.5 mA	1.3	—	2.3	V
Drain-source on-resistance	$R_{DS(ON)}$	V_{GS} = 4.5 V, I_D = 22.5 A	—	2.8	3.6	mΩ
Drain-source on-resistance	$R_{DS(ON)}$	V_{GS} = 10 V, I_D = 22.5 A	—	1.8	2.2	mΩ

Note 6: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	—	2230	—	pF
Reverse transfer capacitance	C_{rss}		—	160	—	pF
Output capacitance	C_{oss}		—	650	—	pF
Switching time (rise time)	t_r	See Fig. 6.2.1	—	9	—	ns
Switching time (turn-on time)	t_{on}		—	14	—	ns
Switching time (fall time)	t_f		—	24	—	ns
Switching time (turn-off time)	t_{off}		—	68	—	ns



Duty ≤ 1%, t_w = 10 μs

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	V_{DD} ≈ 15 V, V_{GS} = 10 V, I_D = 45 A	—	34	—	nC
Gate-source charge 1	Q_{gs1}		—	8	—	nC
Gate-drain charge	Q_{gd}		—	6	—	nC

6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (1 ms) (Note 7)	I_{DRP}	—	—	—	200	A
Diode forward voltage	V_{DSF}	I_{DR} = 45 A, V_{GS} = 0 V	—	—	-1.2	V

Note 7: Ensure that the channel temperature does not exceed 150 °C.

7. Marking

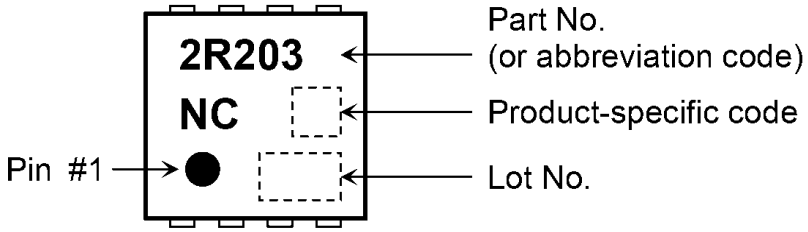


Fig. 7.1 Marking

8. Characteristics Curves (Note)

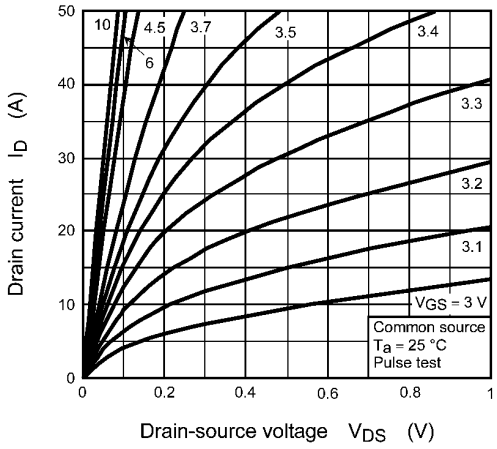


Fig. 8.1 I_D - V_{DS}

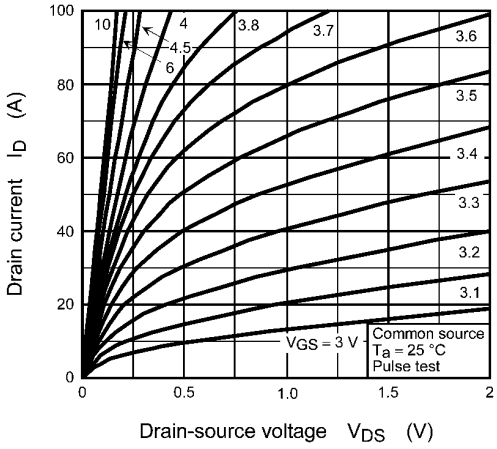


Fig. 8.2 I_D - V_{DS}

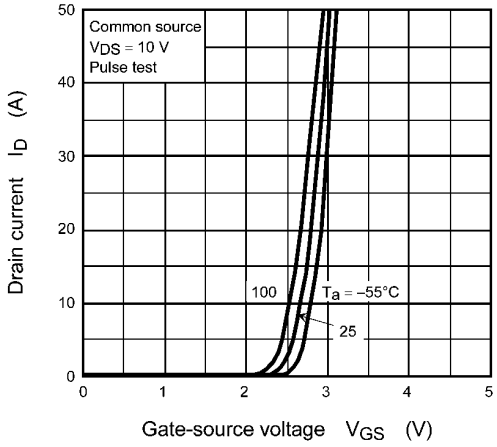


Fig. 8.3 I_D - V_{GS}

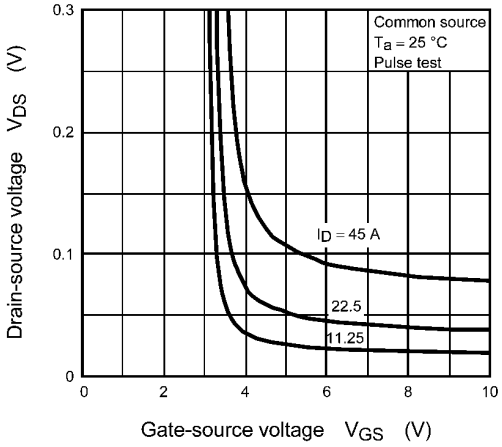


Fig. 8.4 V_{DS} - V_{GS}

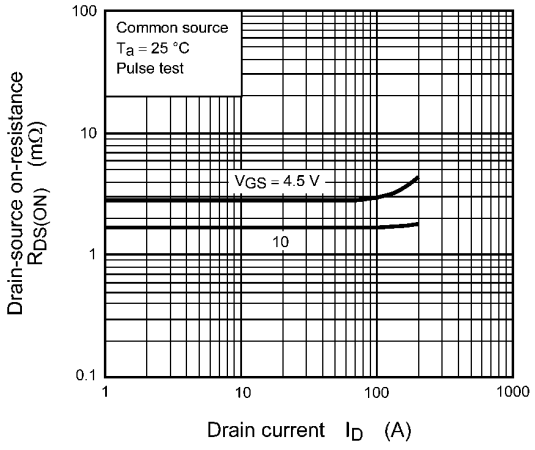


Fig. 8.5 $R_{DS(ON)}$ - I_D

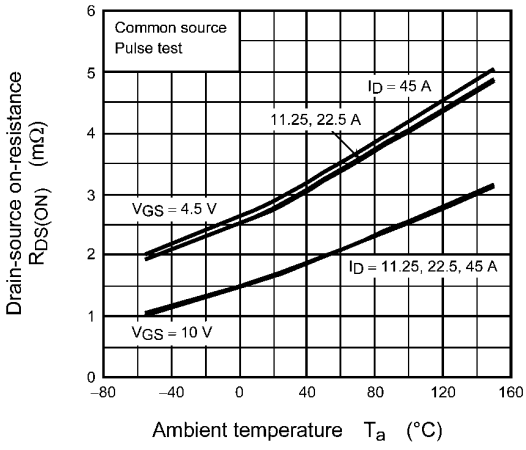


Fig. 8.6 $R_{DS(ON)}$ - T_a

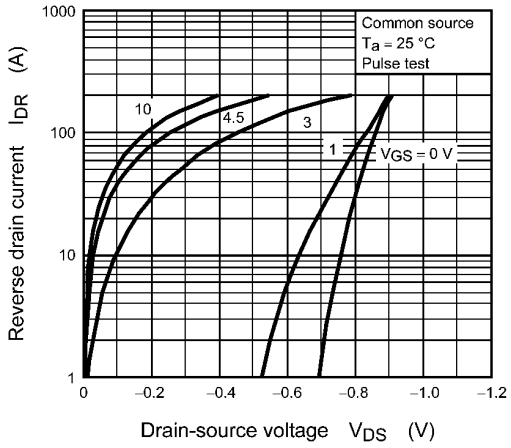


Fig. 8.7 I_{DR} - V_{DS}

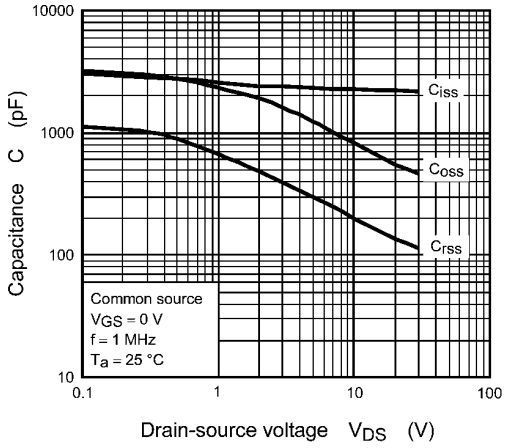


Fig. 8.8 Capacitance - V_{DS}

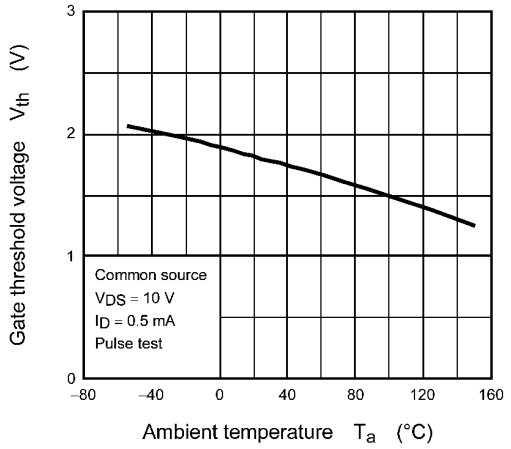


Fig. 8.9 V_{th} - T_a

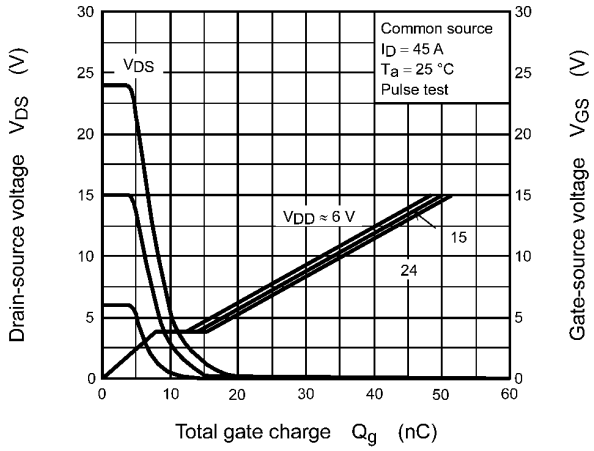


Fig. 8.10 Dynamic Input/Output Characteristics

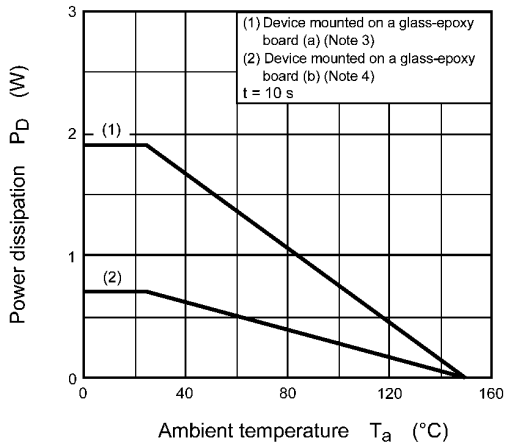


Fig. 8.11 P_D - T_a
(Guaranteed Maximum)

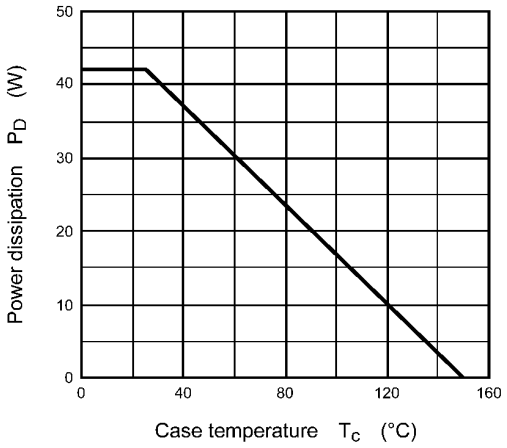


Fig. 8.12 P_D - T_c
(Guaranteed Maximum)

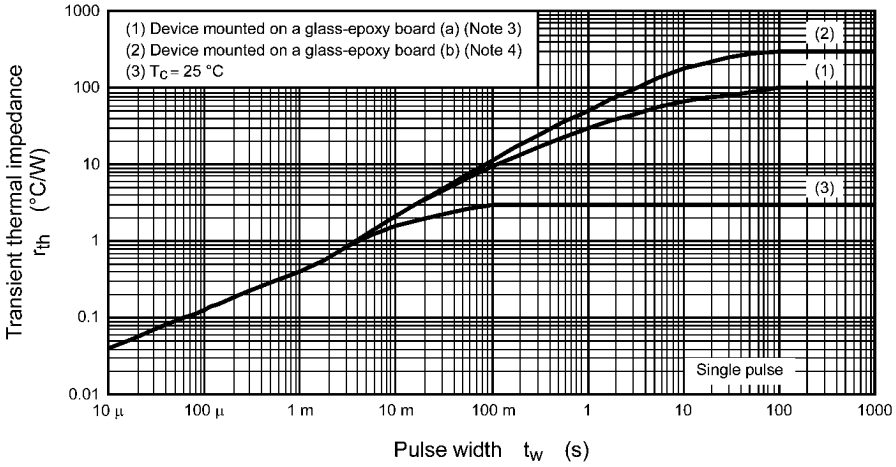


Fig. 8.13 r_{th} - t_w
(Guaranteed Maximum)

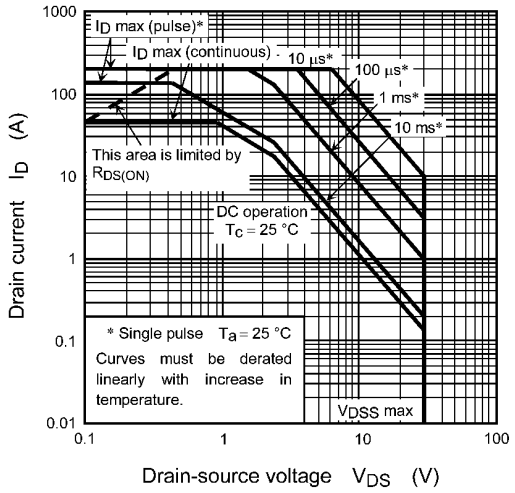
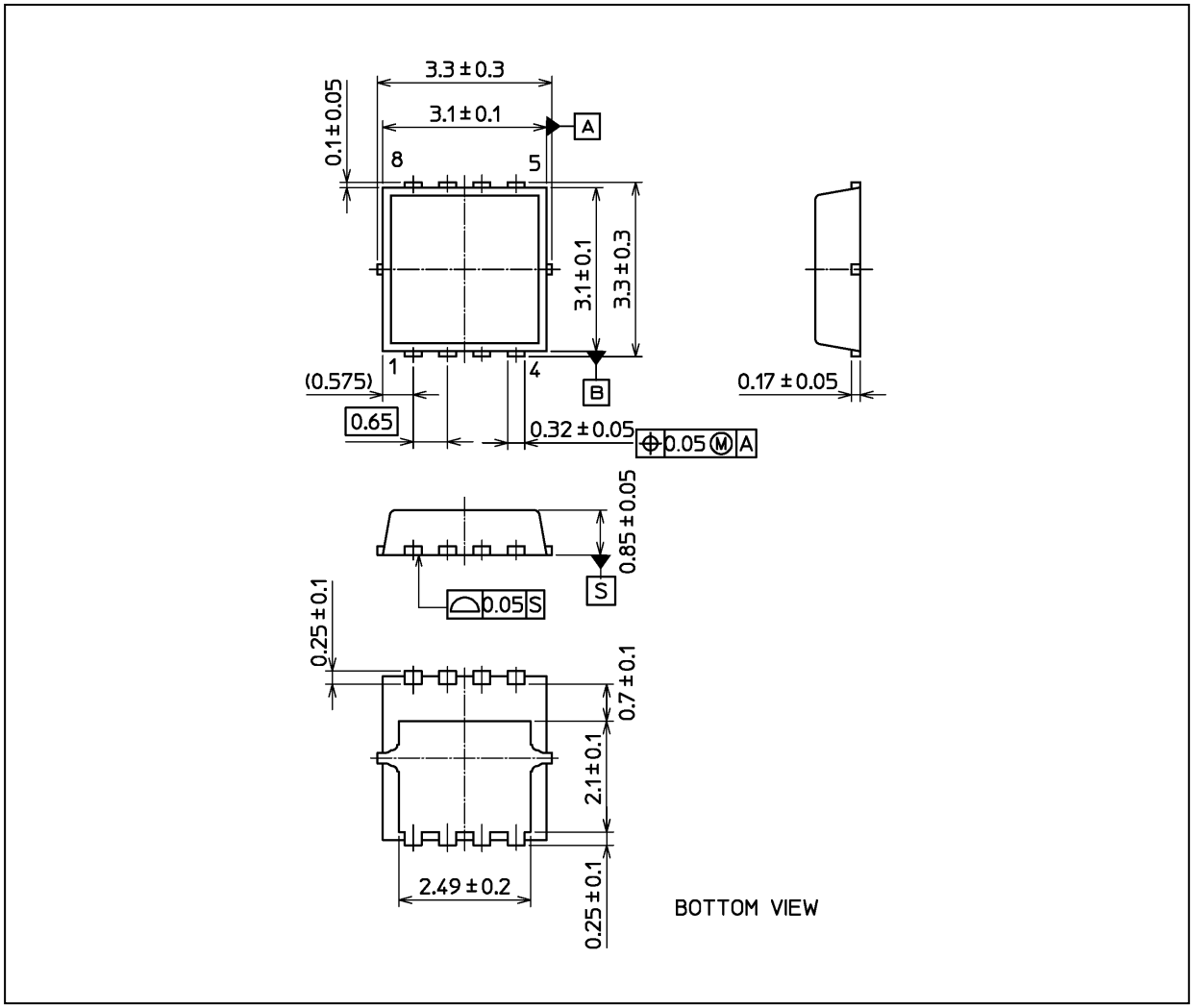


Fig. 8.14 Safe Operating Area
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.02 g (typ.)

Package Name(s)
TOSHIBA: 2-3X1S
Nickname: TSON Advance

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